

## TMP23x-Q1 汽车级高精度模拟输出温度传感器

### 1 特性

- 符合面向汽车应用的 AEC-Q100 标准
  - TMP235-Q1 等级 0:  $-40^{\circ}\text{C}$  至  $+150^{\circ}\text{C}$
  - TMP236-Q1 等级 1:  $-40^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$
- 在宽温度范围内具有高精度:
  - $\pm 2.5^{\circ}\text{C}$  (最大值):  $-40^{\circ}\text{C}$  至  $+150^{\circ}\text{C}$  (TMP235-Q1)
  - $\pm 2.5^{\circ}\text{C}$  (最大值):  $-10^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  (TMP236-Q1)
- 正斜率传感器增益, 失调电压 (典型值):
  - $10\text{mV}/^{\circ}\text{C}$ ,  $0^{\circ}\text{C}$  下  $500\text{mV}$  (TMP235-Q1)
  - $19.5\text{mV}/^{\circ}\text{C}$ ,  $0^{\circ}\text{C}$  下  $400\text{mV}$  (TMP236-Q1)
- 宽工作电源电压范围:
  - $2.3\text{V}$  至  $5.5\text{V}$  (TMP235-Q1)
  - $3.1\text{V}$  至  $5.5\text{V}$  (TMP236-Q1)
- 输出短路保护
- 低功耗:  $9\mu\text{A}$  (典型值)
- 输出强大, 可驱动高达  $1000\text{pF}$  的负载
- 提供的封装选项:
  - 5 引脚 SC70 (DCK) 表面贴装
  - 3 引脚 SOT-23 (DBZ) 表面贴装
  - 封装尺寸兼容业界通用的 LMT8x-Q1、LM50-Q1 和 LM20 温度传感器
- 具有成本效益的热敏电阻替代产品

### 2 应用

- 汽车音响主机
- 电动助力转向 (EPS)
- 换挡系统
- 电池管理系统 (BMS)
- 汽油发动机

### 3 说明

TMP23x-Q1 器件是一系列汽车级精密 CMOS 集成电路线性模拟温度传感器, 其输出电压与温度成正比, 可用于从动力系统到信息娱乐系统等多种汽车应用。这些温度传感器具有  $\pm 0.5^{\circ}\text{C}$  的典型精度。TMP235-Q1 器件在  $-40^{\circ}\text{C}$  至  $+150^{\circ}\text{C}$  完全温度范围和  $2.3\text{V}$  至  $5.5\text{V}$  电源电压范围内提供  $10\text{mV}/^{\circ}\text{C}$  正斜率输出。具有更高增益的 TMP236-Q1 传感器在  $-10^{\circ}\text{C}$  至  $+125^{\circ}\text{C}$  温度范围和  $3.1\text{V}$  至  $5.5\text{V}$  电源电压范围内提供  $19.5\text{mV}/^{\circ}\text{C}$  正斜率输出。

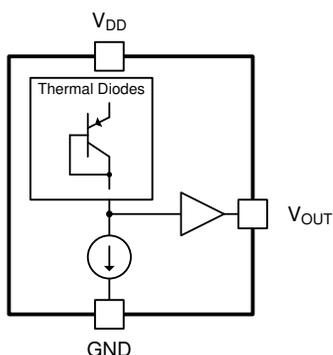
$9\mu\text{A}$  典型静态电流和  $800\mu\text{s}$  典型加电时间可实现有效的功率循环架构, 以最大限度地降低电池供电设备的功率损耗。AB 类输出驱动器提供强大的  $500\mu\text{A}$  最高输出, 可驱动高达  $1000\text{pF}$  的电容负载, 并可直接连接到模数转换器采样保持输入端。凭借出色的精确度和强大的线性输出驱动器, TMP23x-Q1 模拟输出温度传感器是具有成本效益的无源热敏电阻替代方案。

#### 器件信息<sup>(1)</sup>

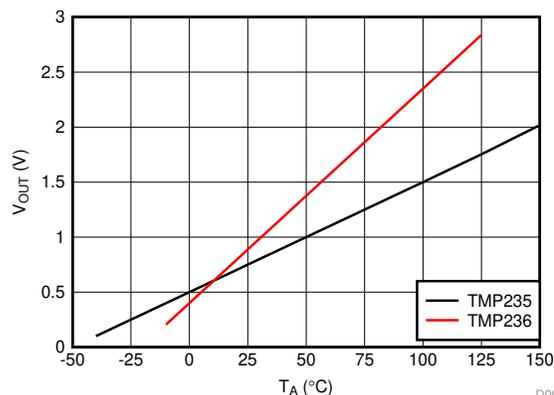
器件型号	封装	封装尺寸 (标称值)
TMP235-Q1, TMP236-Q1	SC70 (5)	2.00mm x 1.25mm
	SOT-23 (3)	2.92mm x 1.30mm

(1) 如需了解所有可用封装, 请参阅产品说明书末尾的可订购产品附录。

功能方框图



输出电压与环境温度间的关系



D003



## 目录

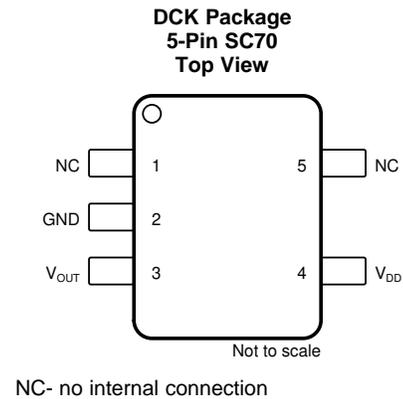
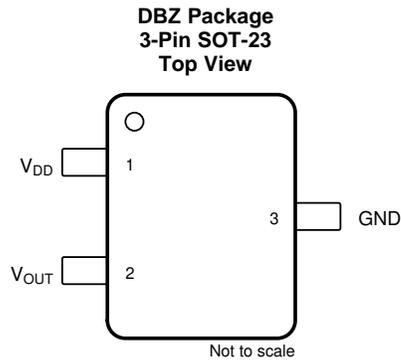
<ul style="list-style-type: none"> <li>1 特性 ..... 1</li> <li>2 应用 ..... 1</li> <li>3 说明 ..... 1</li> <li>4 修订历史记录 ..... 2</li> <li>5 <b>Pin Configuration and Functions</b> ..... 3</li> <li>6 <b>Specifications</b> ..... 4           <ul style="list-style-type: none"> <li>6.1 Absolute Maximum Ratings ..... 4</li> <li>6.2 ESD Ratings ..... 4</li> <li>6.3 Recommended Operating Conditions ..... 4</li> <li>6.4 Thermal Information ..... 4</li> <li>6.5 Electrical Characteristics ..... 5</li> <li>6.6 Typical Characteristics ..... 6</li> </ul> </li> <li>7 <b>Detailed Description</b> ..... 8           <ul style="list-style-type: none"> <li>7.1 Overview ..... 8</li> <li>7.2 Functional Block Diagram ..... 8</li> <li>7.3 Feature Description ..... 8</li> </ul> </li> </ul>	<ul style="list-style-type: none"> <li>7.4 Device Functional Modes ..... 10</li> <li>8 <b>Application and Implementation</b> ..... 11           <ul style="list-style-type: none"> <li>8.1 Application Information ..... 11</li> <li>8.2 Typical Application ..... 11</li> </ul> </li> <li>9 <b>Power Supply Recommendations</b> ..... 12</li> <li>10 <b>Layout</b> ..... 12           <ul style="list-style-type: none"> <li>10.1 Layout Guidelines ..... 12</li> <li>10.2 Layout Examples ..... 12</li> </ul> </li> <li>11 <b>器件和文档支持</b> ..... 13           <ul style="list-style-type: none"> <li>11.1 相关链接 ..... 13</li> <li>11.2 接收文档更新通知 ..... 13</li> <li>11.3 支持资源 ..... 13</li> <li>11.4 商标 ..... 13</li> <li>11.5 静电放电警告 ..... 13</li> <li>11.6 Glossary ..... 13</li> </ul> </li> <li>12 <b>机械、封装和可订购信息</b> ..... 13</li> </ul>
--	---

## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

<b>Changes from Revision B (October 2019) to Revision C</b>	<b>Page</b>
<ul style="list-style-type: none"> <li>• Added temperature accuracy specs for the TMP236-Q1 SOT-23 package ..... 5</li> </ul>	5
<b>Changes from Revision A (May 2019) to Revision B</b>	<b>Page</b>
<ul style="list-style-type: none"> <li>• 已更改 将文档状态从“预告信息”更改为“生产数据” ..... 1</li> </ul>	1
<b>Changes from Original (April 2019) to Revision A</b>	<b>Page</b>
<ul style="list-style-type: none"> <li>• Changed recommended operating temperature range from: –50°C to 150°C to: –40°C to 150°C ..... 4</li> </ul>	4

## 5 Pin Configuration and Functions



### Pin Functions

NAME	PIN		TYPE	DESCRIPTION
	SOT-23	SC70		
GND	3	2	Ground	Power supply ground.
NC	—	5	—	No internal connection. This pin may be left floating or connected to GND.
NC	—	1	—	No internal connection. This pin may be left floating or connected to GND.
V <sub>OUT</sub>	2	3	O	Outputs voltage proportional to temperature
V <sub>DD</sub>	1	4	I	Positive supply input

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

	MIN	MAX	UNIT
Supply voltage, $V_{DD}$		+6	V
Output voltage, $V_{OUT}$	-0.3	( $V_{DD} + 0.3$ )	
Output current	-30	+30	mA
Latch-up current, each pin	-200	+200	
Junction temperature ( $T_J$ )		+150	°C
Storage temperature ( $T_{stg}$ )	-65	+150	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

			VALUE	UNIT	
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup> HBM ESD Classification Level 2	±2000	V	
		Charged device model (CDM), per AEC Q100-011 CDM ESD Classification Level C4B	All Pins	±500	V
			Corner Pins	±750	V

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{DD}$	Input voltage (TMP235-Q1)	2.3		5.5	V
	Input voltage (TMP236-Q1)	3.1		5.5	
$T_A$	Operating free-air temperature	-40		150	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)(2)</sup>		TMP23X-Q1		UNIT
		DCK (SC70)	DBZ (SOT-23)	
		5 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(3)(4)</sup>	275	167	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	84	90	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	56	146	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	1.2	35	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	55	146	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) For information on self-heating and thermal response time see [Layout Guidelines](#) section.
- (3) The junction to ambient thermal resistance ( $R_{\theta JA}$ ) under natural convection is obtained in a simulation on a JEDEC-standard, High-K board as specified in JESD51-7, in an environment described in JESD51-2. Exposed pad packages assume that thermal vias are included in the PCB, per JESD 51-5.
- (4) Changes in output due to self heating can be computed by multiplying the internal dissipation by the thermal resistance.

## 6.5 Electrical Characteristics

TMP235-Q1:  $V_{DD} = 2.3\text{ V to }5.5\text{ V}$ , GND = Ground,  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$  and no load (unless otherwise noted)

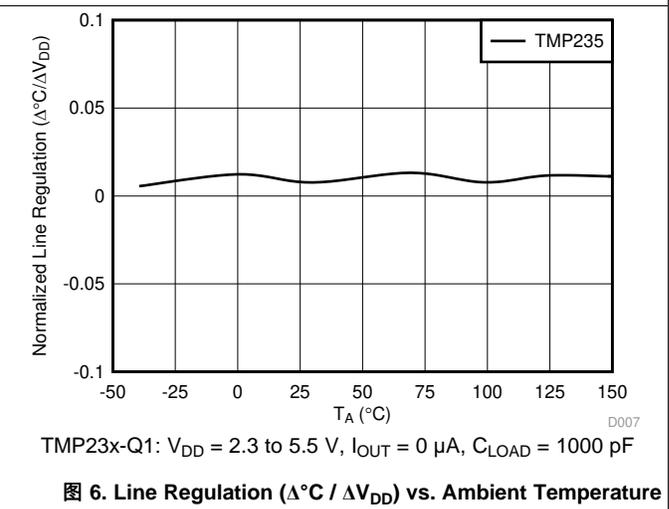
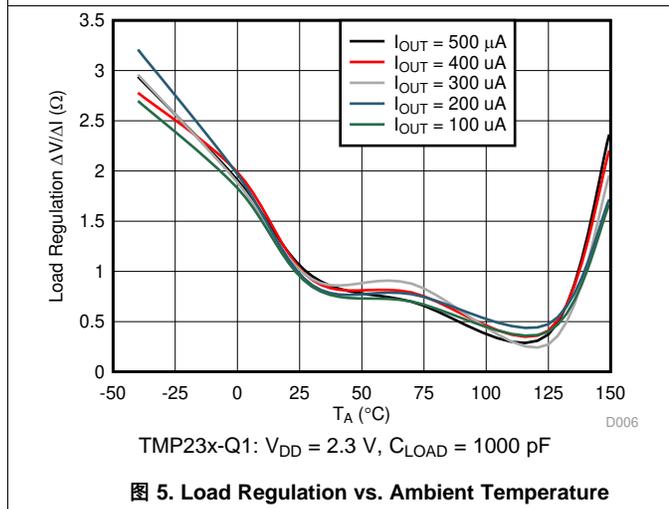
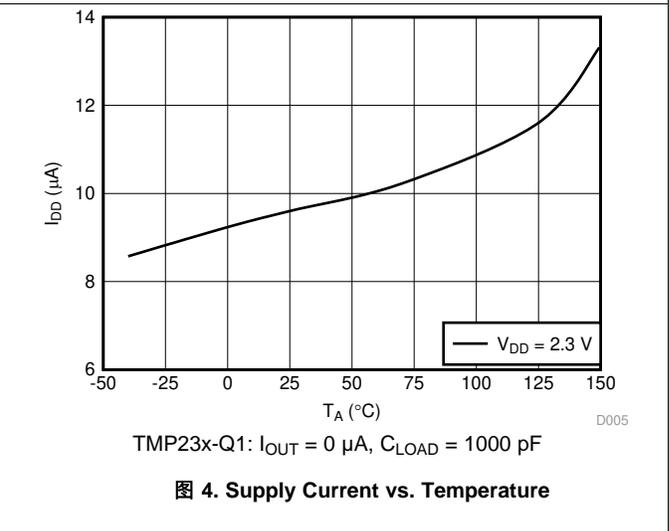
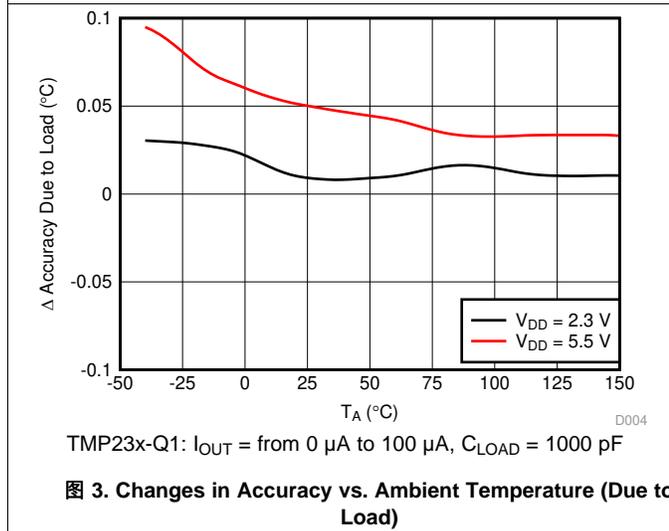
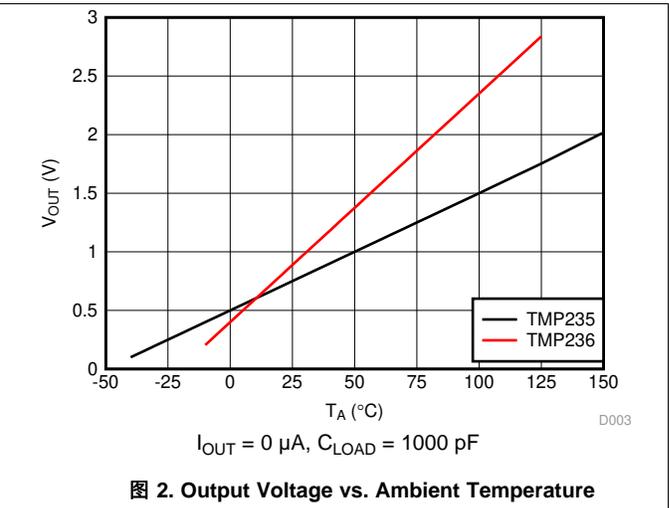
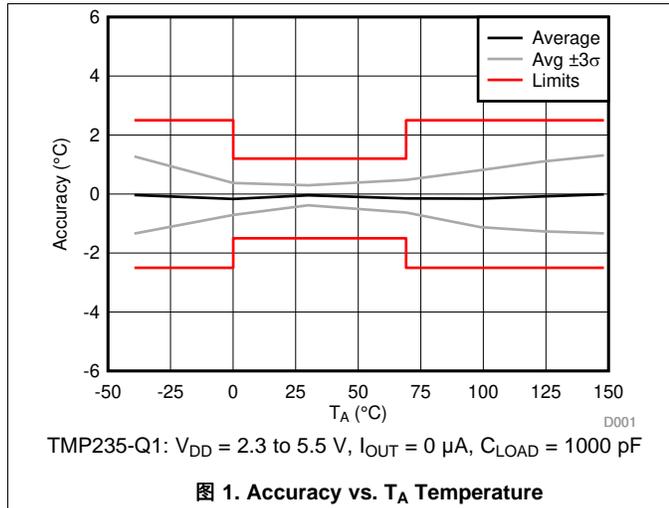
TMP236-Q1:  $V_{DD} = 3.1\text{ V to }5.5\text{ V}$ , GND = Ground,  $T_A = -10^\circ\text{C to }+125^\circ\text{C}$  and no load (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>POWER SUPPLY</b>							
$I_{DD}$	Operating current	$T_A = 25^\circ\text{C}$ , $V_{DD} = 2.3\text{ V}$ , TMP235-Q1		9		$\mu\text{A}$	
		$T_A = 25^\circ\text{C}$ , $V_{DD} = 3.1\text{ V}$ , TMP236-Q1		10			
		$T_A = -40^\circ\text{C to }+125^\circ\text{C}$ , TMP235-Q1			14.5		
		$T_A = -10^\circ\text{C to }+125^\circ\text{C}$ , TMP236-Q1			15		
		$T_A = 150^\circ\text{C}$ , TMP235-Q1			17		
$\frac{\Delta^\circ\text{C}}{\Delta V_{DD}}$	Line regulation		-0.1	0.02	0.1	$^\circ\text{C/V}$	
<b>SENSOR ACCURACY</b>							
$T_{ACY}$	Temperature accuracy <sup>(1)</sup>	$T_A = 25^\circ\text{C}$		$\pm 0.5$		$^\circ\text{C}$	
		$T_A = 0^\circ\text{C to }70^\circ\text{C}$ (SC70 Package) (TMP235-Q1)	-1.5	$\pm 0.5$	+1.2		
		$T_A = 0^\circ\text{C to }70^\circ\text{C}$ (SOT-23 Package) (TMP235-Q1)	-1.5	$\pm 0.5$	+1.2		
		$T_A = -40^\circ\text{C to }125^\circ\text{C}$ (TMP235-Q1)	-2.5	$\pm 0.5$	+2.5		
		$T_A = -40^\circ\text{C to }150^\circ\text{C}$ (TMP235-Q1)	-2.5	$\pm 0.5$	+2.5		
		$T_A = -10^\circ\text{C to }125^\circ\text{C}$ (TMP236-Q1)	-2.5	$\pm 0.5$	+2.5		
$T_{ACY}$	Temperature accuracy <sup>(1)</sup>	$T_A = 0^\circ\text{C to }70^\circ\text{C}$ (SOT-23 Package) (TMP236-Q1)	-1.5	$\pm 0.5$	+1.5	$^\circ\text{C}$	
<b>SENSOR OUTPUT</b>							
$V_{0^\circ\text{C}}$	Output voltage offset at $0^\circ\text{C}$	TMP235-Q1		500		mV	
		TMP236-Q1		400			
$T_C$	Temperature coefficient (sensor gain)	TMP235-Q1		10		mV/ $^\circ\text{C}$	
		TMP236-Q1		19.5			
$V_{ONL}$	Output nonlinearity <sup>(2)</sup>	$T_A = 0^\circ\text{C to }70^\circ\text{C}$ , no load		$\pm 0.5$		$^\circ\text{C}$	
$I_{OUT}$	Output current				500	$\mu\text{A}$	
$Z_{OUT}$	Output impedance	$I_{OUT} = 100\ \mu\text{A}$ , $f = 100\text{ Hz}$		20		$\Omega$	
		$I_{OUT} = 100\ \mu\text{A}$ , $f = 500\text{ Hz}$		50			
	Output load regulation	$T_A = 0^\circ\text{C to }70^\circ\text{C}$ , $I_{OUT} = 100\ \mu\text{A}$ , $\Delta V_{OUT} / \Delta I_{OUT}$		1		$\Omega$	
$t_{ON}$	Turn on time	Time to reach accuracy within $\pm 0.5^\circ\text{C}$		800		$\mu\text{s}$	
$C_{LOAD}$	Typical load capacitance				1000	pF	
$t_{RES}$	Thermal response to 63%	SC70	$30^\circ\text{C}$ (Air) to $+125^\circ\text{C}$ (Fluid Bath)		1.3	s	

- (1) Accuracy is defined as the error between the measured and reference output voltages, tabulated in the [TMP235-Q1 Transfer Table](#) and [TMP236-Q1 Transfer Table](#) at the specified conditions of supply voltage and temperature (expressed in  $^\circ\text{C}$ ). Accuracy limits include line regulation within the specified conditions. Accuracy limits do not include load regulation; they assume no DC load.
- (2) Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the device's rated temperature range.

### 6.6 Typical Characteristics

at  $T_A = 25^\circ\text{C}$ , (unless otherwise noted)



Typical Characteristics (接下页)

at  $T_A = 25^\circ\text{C}$ , (unless otherwise noted)

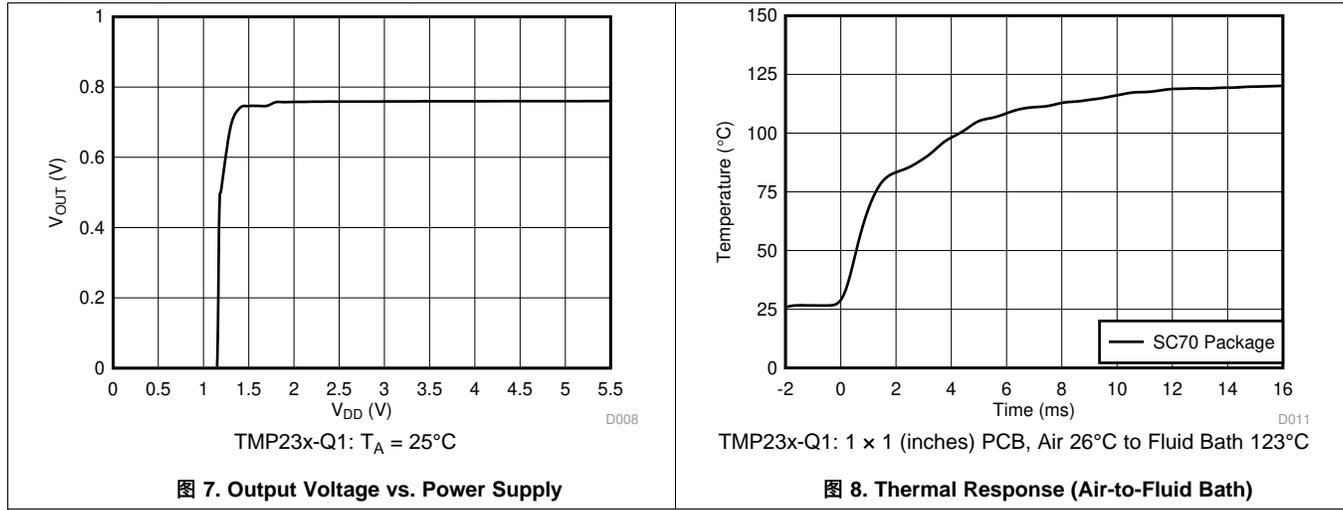


图 7. Output Voltage vs. Power Supply

图 8. Thermal Response (Air-to-Fluid Bath)

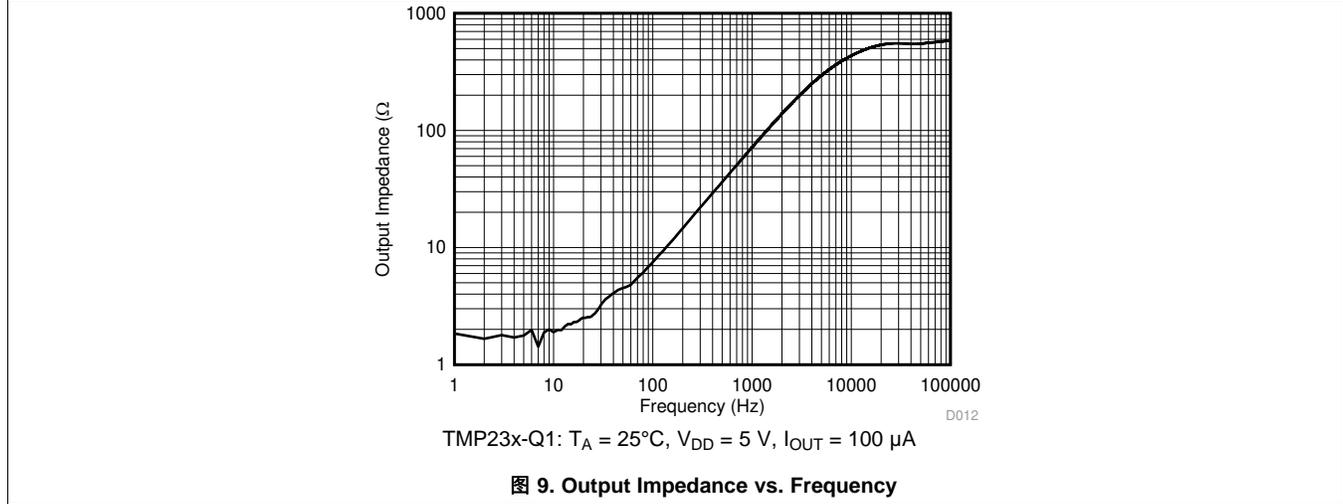


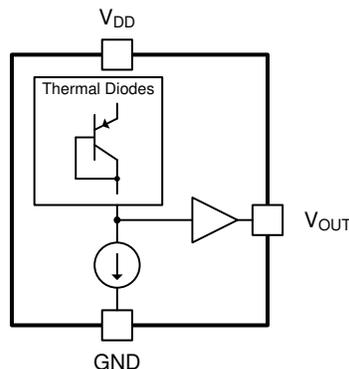
图 9. Output Impedance vs. Frequency

## 7 Detailed Description

### 7.1 Overview

The TMP23x-Q1 devices are a family of linear analog temperature sensors with an output voltage proportional to temperature. These temperature sensors have an accuracy from 0°C to 70°C of ±1.5°C. The TMP235-Q1 device provides a positive slope output of 10 mV/°C over the full –40°C to +150°C temperature range and a supply range from 2.3 V to 5.5 V. The higher gain TMP236-Q1 sensor provides a positive slope output of 19.5 mV/°C from –10°C to +125°C and a supply range from 3.1 V to 5.5 V. A class-AB output driver provides a maximum output of 500 µA to drive capacitive loads up to 1000 pF.

### 7.2 Functional Block Diagram



### 7.3 Feature Description

As shown in 图 2, the TMP23x-Q1 devices are linear. A small  $V_{OUT}$  gain shift, however, is present at temperatures above 100°C. When small shifts are expected, a piecewise linear function provides the best accuracy and is used for the device accuracy specifications (see [Specifications](#)). Typical output voltages of the TMP23x-Q1 devices across the full operating temperature range are listed in 表 3 and 表 4. The ideal linear columns represent the ideal linear  $V_{OUT}$  output response with respect to temperature, while the piecewise linear columns indicate the small voltage shift at elevated temperatures.

The piecewise linear function uses three temperature ranges listed in 表 1 and 表 2. In equation form, the voltage output  $V_{OUT}$  of the TMP23x-Q1 is calculated by 公式 1:

$$V_{OUT} = (T_A - T_{INFL}) \times T_C + V_{OFFS}$$

where

- $V_{OUT}$  is the TMP23x-Q1 voltage output for a given temperature
- $T_A$  is the ambient temperature in °C
- $T_{INFL}$  is the temperature inflection point for a piecewise segment in °C
- $T_C$  is the TMP23x-Q1 temperature coefficient or gain
- $V_{OFFS}$  is the TMP23x-Q1 voltage offset

(1)

Therefore, the  $T_A$  temperature for a given  $V_{OUT}$  voltage output within a piecewise voltage range ( $V_{RANGE}$ ) is calculated in 公式 2. For applications where the accuracy enhancement above 100°C is not required, use the first row of 表 1 and 表 2 for all voltages.

$$T_A = (V_{OUT} - V_{OFFS}) / T_C + T_{INFL}$$

(2)

**表 1. TMP235-Q1 Piecewise Linear Function Summary**

$T_A$ RANGE (°C)	$V_{RANGE}$ (mV)	$T_{INFL}$ (°C)	$T_C$ (mV/°C)	$V_{OFFS}$ (mV)
–40 to +100	< 1500	0	10	500
100 to 125	1500 to 1752.5	100	10.1	1500
125 to 150	> 1752.5	125	10.6	1752.5

**表 2. TMP236-Q1 Piecewise Linear Function Summary**

T <sub>A</sub> RANGE (°C)	V <sub>RANGE</sub> (mV)	T <sub>INFL</sub> (°C)	T <sub>C</sub> (mV/°C)	V <sub>OFFS</sub> (mV)
-40 to +100	≤ 2350	0	19.5	400
100 to 125	> 2350	100	19.7	2350
125 to 150	—	—	—	—

**表 3. TMP235-Q1 Transfer Table**

TEMPERATURE (°C)	V <sub>OUT</sub> (mV) IDEAL LINEAR VALUES	V <sub>OUT</sub> (mV) PIECEWISE LINEAR VALUES
-40	100	100
-35	150	150
-30	200	200
-25	250	250
-20	300	300
-15	350	350
-10	400	400
-5	450	450
0	500	500
5	550	550
10	600	600
15	650	650
20	700	700
25	750	750
30	800	800
35	850	850
40	900	900
45	950	950
50	1000	1000
55	1050	1050
60	1100	1100
65	1150	1150
70	1200	1200
75	1250	1250
80	1300	1300
85	1350	1350
90	1400	1400
95	1450	1450
100	1500	1500
105	1550	1550.5
110	1600	1601
115	1650	1651.5
120	1700	1702
125	1750	1752.5
130	1800	1805.5
135	1850	1858.5
140	1900	1911.5
145	1950	1964.5
150	2000	2017.5

**表 4. TMP236-Q1 Transfer Table**

TEMPERATURE (°C)	V <sub>OUT</sub> (mV) IDEAL LINEAR VALUES	V <sub>OUT</sub> (mV) PIECEWISE LINEAR VALUES
-40	—	—
-35	—	—
-30	—	—
-25	—	—
-20	—	—
-15	—	—
-10	205	205
-5	303	303
0	400	400
5	498	498
10	595	595
15	693	693
20	790	790
25	888	888
30	985	985
35	1083	1083
40	1180	1180
45	1278	1278
50	1375	1375
55	1473	1473
60	1570	1570
65	1668	1668
70	1765	1765
75	1863	1863
80	1960	1960
85	2058	2058
90	2155	2155
95	2253	2253
100	2350	2350
105	2448	2448.5
110	2545	2547
115	2643	2645.4
120	2740	2743.9
125	2838	2842.4
130	—	—
135	—	—
140	—	—
145	—	—
150	—	—

## 7.4 Device Functional Modes

The singular functional mode of the TMP23x-Q1 is an analog output directly proportional to temperature.

## 8 Application and Implementation

### NOTE

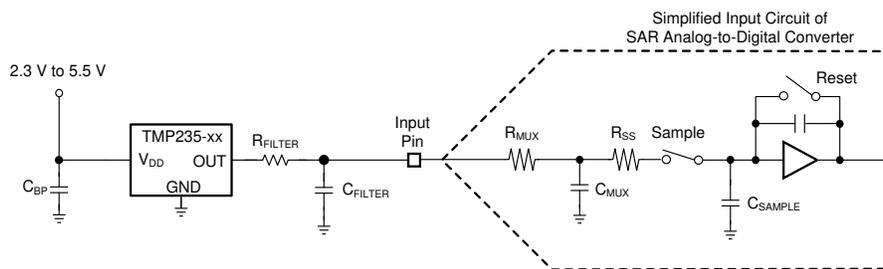
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The features of the TMP235-Q1 make the series of devices designed for various general temperature-sensing applications. The TMP235-Q1 and TMP236-Q1 devices can operate down to a 2.3-V and a 3.1-V supply with 9- $\mu$ A power consumption, respectively. The TMP23x-Q1 series is mounted in two surface mount technology packages (SC70 and SOT-23.)

### 8.2 Typical Application

#### 8.2.1 Connection to an ADC



**Figure 10. Suggested Connections to an ADC Input Stage**

##### 8.2.1.1 Design Requirements

See [Figure 10](#) for suggested connections to an ADC input stage. Most CMOS-based ADCs have a sampled data comparator input structure. When the ADC charges the sampling capacitor ( $C_{SAMPLE}$ ), the capacitor requires instantaneous charge from the output of the analog source temperature sensor, such as the TMP235-Q1. Therefore, the output impedance of the temperature sensor can affect ADC performance. In most cases, adding an external capacitor ( $C_{FILTER}$ ) mitigates design challenges. The TMP235-Q1 is specified and characterized with a 1000-pF maximum capacitive load ( $C_{LOAD}$ ). [Figure 10](#) shows  $C_{LOAD}$  as the sum of  $C_{FILTER} + C_{MUX} + C_{SAMPLE}$ . TI recommends maximizing the  $C_{FILTER}$  value while allowing for the maximum specified ADC input capacitance ( $C_{MUX} + C_{SAMPLE}$ ) to limit the total  $C_{LOAD}$  at 1000 pF. In most cases, a 680-pF  $C_{FILTER}$  provides a reasonable allowance for ADC input capacitance to minimize ADC sampling error and reduce noise coupling. An optional series resistor ( $R_{FILTER}$ ) and  $C_{FILTER}$  provides additional low-pass filtering to reject system level noise. TI recommends placing  $R_{FILTER}$  and  $C_{FILTER}$  as close as possible to the ADC input for optimal performance.

##### 8.2.1.2 Detailed Design Procedure

Depending on the input characteristics of the ADC, an external  $C_{FILTER}$  may be required. The value of  $C_{FILTER}$  depends on the size of the sampling capacitor ( $C_{SAMPLE}$ ) and the sampling frequency while observing a maximum  $C_{LOAD}$  of 1000 pF. The capacitor requirements can vary because the input stages of all ADCs are not identical. [Figure 10](#) shows a general ADC application as an example only.

## Typical Application (continued)

### 8.2.1.3 Application Curve

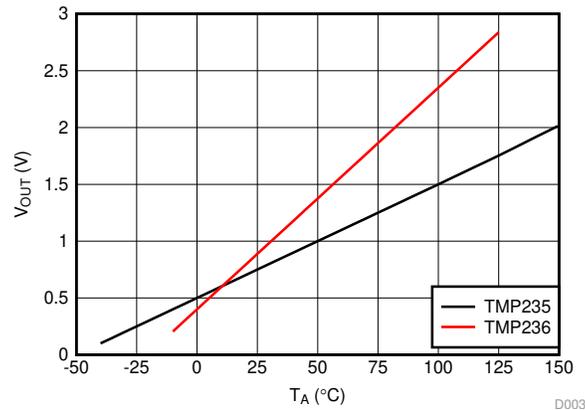


Figure 11. Output Voltage vs. Ambient

## 9 Power Supply Recommendations

The low supply current and supply range of the TMP23x-Q1 allow the device to be easily powered from many sources.

Power supply bypassing is strongly recommended. In noisy environments, TI recommends to add a filter with 0.1- $\mu$ F capacitor and 100- $\Omega$  resistor between external supply and  $V_{DD}$  to limit the power supply noise. Larger capacitances may be required and are dependent on the noise of the power supply.

## 10 Layout

### 10.1 Layout Guidelines

The layout of the TMP23x-Q1 series is simple. If a power supply bypass capacitor is used, the capacitor must be connected as [Layout Examples](#) shows.

### 10.2 Layout Examples

 VIA to ground plane

 VIA to power plane

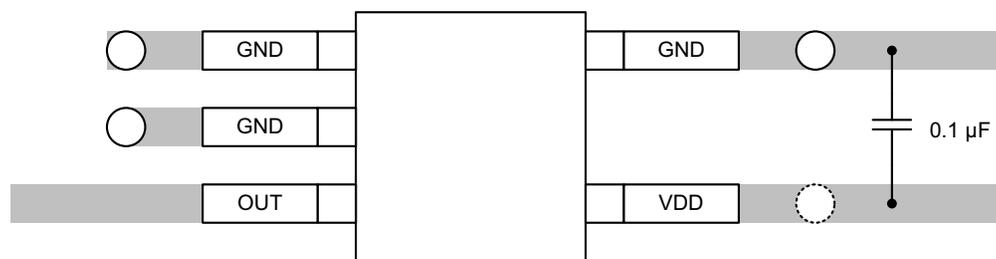


Figure 12. Recommended Layout: SC70 Package

## 11 器件和文档支持

### 11.1 相关链接

下表列出了快速访问链接。类别包括技术文档、支持和社区资源、工具和软件，以及立即订购快速访问。

表 5. 相关链接

器件	产品文件夹	立即订购	技术文档	工具与软件	支持和社区
TMP235-Q1	<a href="#">单击此处</a>				
TMP236-Q1	<a href="#">单击此处</a>				

### 11.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](http://ti.com) 上的器件产品文件夹。单击右上角的通知我进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 11.3 支持资源

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 11.4 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 11.5 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

## 重要声明和免责声明

TI 均以“原样”提供技术性及其可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对TI 及其代表造成的损害。

TI 所提供产品均受TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及ti.com.cn上或随附TI产品提供的其他可适用条款的约束。TI提供所述资源并不扩展或以其他方式更改TI 针对TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122  
Copyright © 2020 德州仪器半导体技术（上海）有限公司

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TMP235AEDBZRQ1	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 150	235E	<a href="#">Samples</a>
TMP235AEDBZTQ1	ACTIVE	SOT-23	DBZ	3	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 150	235E	<a href="#">Samples</a>
TMP235AEDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 150	1CF	<a href="#">Samples</a>
TMP235AEDCKTQ1	ACTIVE	SC70	DCK	5	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 150	1CF	<a href="#">Samples</a>
TMP235AQDBZRQ1	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	235Q	<a href="#">Samples</a>
TMP235AQDBZTQ1	ACTIVE	SOT-23	DBZ	3	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	235Q	<a href="#">Samples</a>
TMP235AQDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CG	<a href="#">Samples</a>
TMP235AQDCKTQ1	ACTIVE	SC70	DCK	5	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1CG	<a href="#">Samples</a>
TMP236AQDBZRQ1	ACTIVE	SOT-23	DBZ	3	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	236Q	<a href="#">Samples</a>
TMP236AQDBZTQ1	ACTIVE	SOT-23	DBZ	3	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	236Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

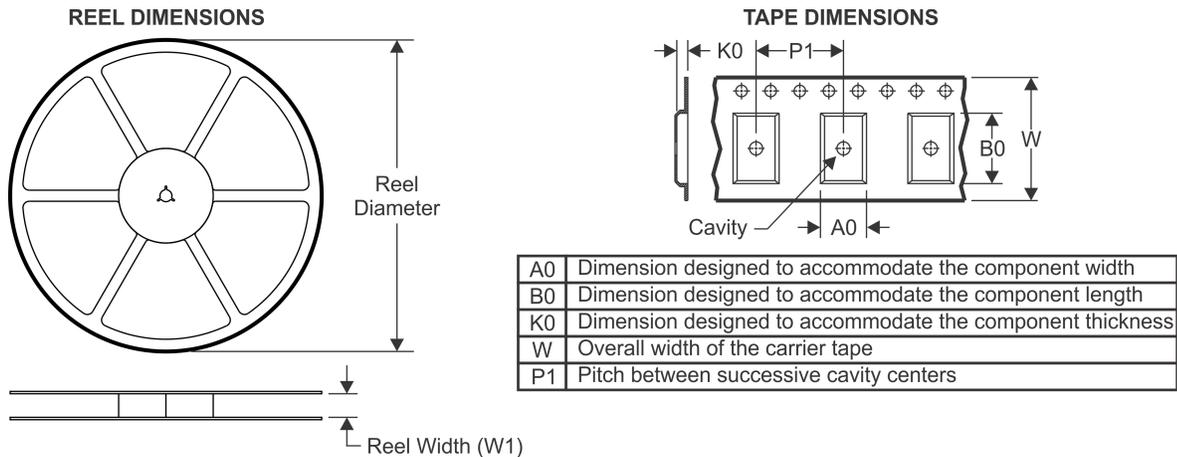
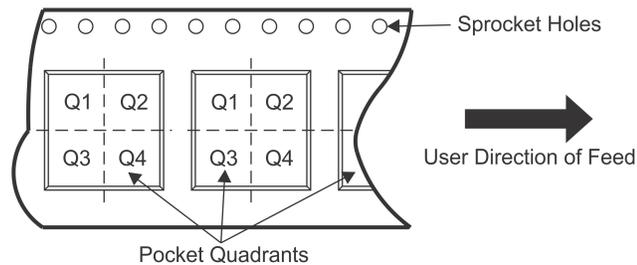
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

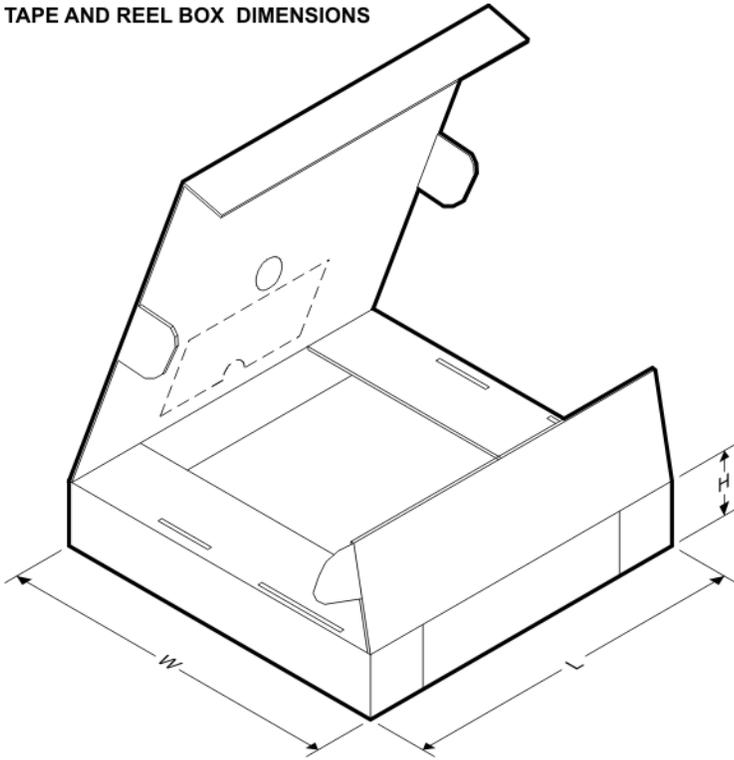
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMP235AEDBZRQ1	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TMP235AEDBZTQ1	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TMP235AEDCKRQ1	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
TMP235AEDCKTQ1	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
TMP235AQDBZRQ1	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TMP235AQDBZTQ1	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TMP235AQDCKRQ1	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
TMP235AQDCKTQ1	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
TMP236AQDBZRQ1	SOT-23	DBZ	3	3000	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3
TMP236AQDBZTQ1	SOT-23	DBZ	3	250	180.0	8.4	3.15	2.77	1.22	4.0	8.0	Q3

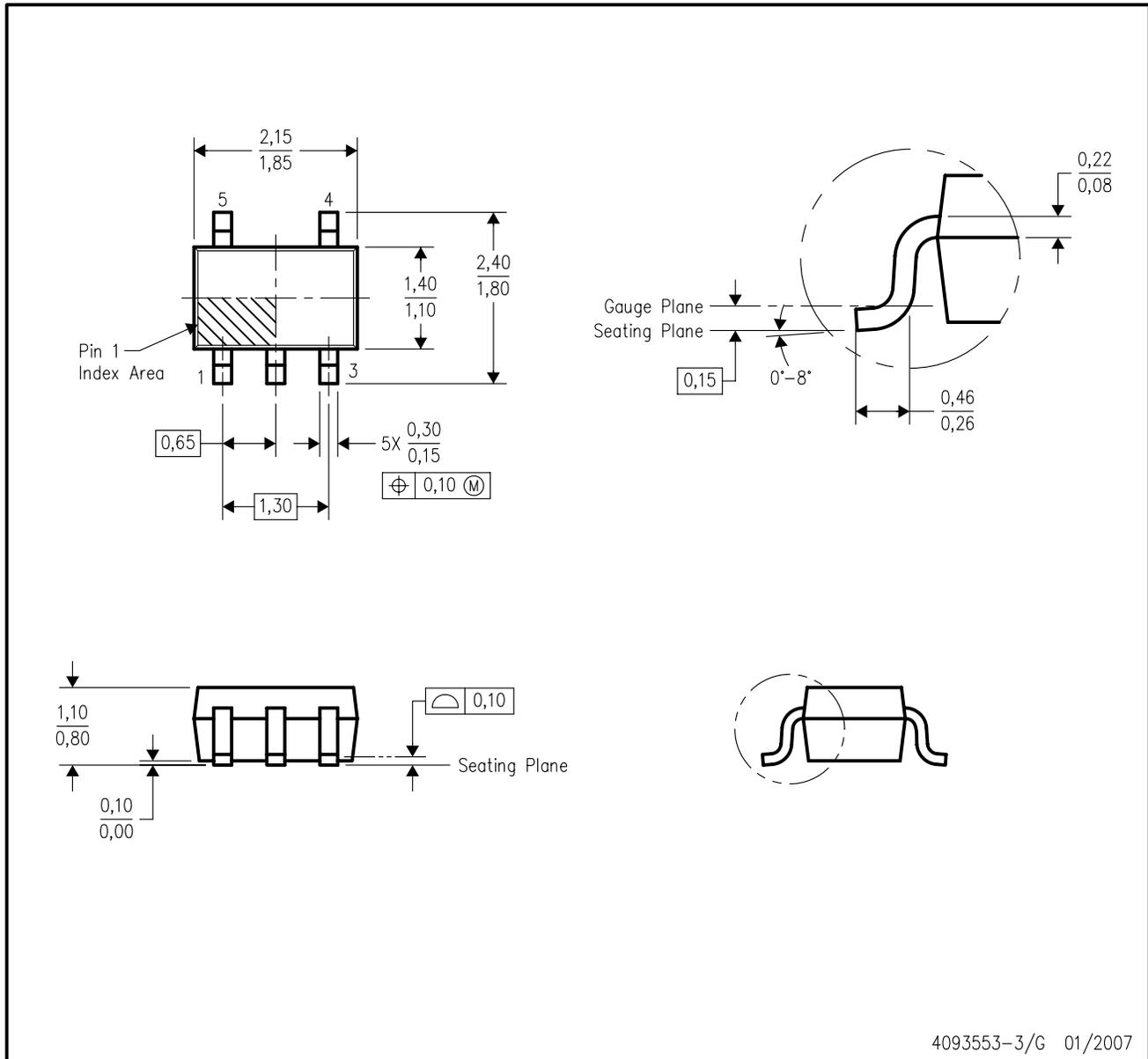
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMP235AEDBZRQ1	SOT-23	DBZ	3	3000	213.0	191.0	35.0
TMP235AEDBZTQ1	SOT-23	DBZ	3	250	213.0	191.0	35.0
TMP235AEDCKRQ1	SC70	DCK	5	3000	213.0	191.0	35.0
TMP235AEDCKTQ1	SC70	DCK	5	250	213.0	191.0	35.0
TMP235AQDBZRQ1	SOT-23	DBZ	3	3000	213.0	191.0	35.0
TMP235AQDBZTQ1	SOT-23	DBZ	3	250	213.0	191.0	35.0
TMP235AQDCKRQ1	SC70	DCK	5	3000	213.0	191.0	35.0
TMP235AQDCKTQ1	SC70	DCK	5	250	213.0	191.0	35.0
TMP236AQDBZRQ1	SOT-23	DBZ	3	3000	213.0	191.0	35.0
TMP236AQDBZTQ1	SOT-23	DBZ	3	250	213.0	191.0	35.0

DCK (R-PDSO-G5)

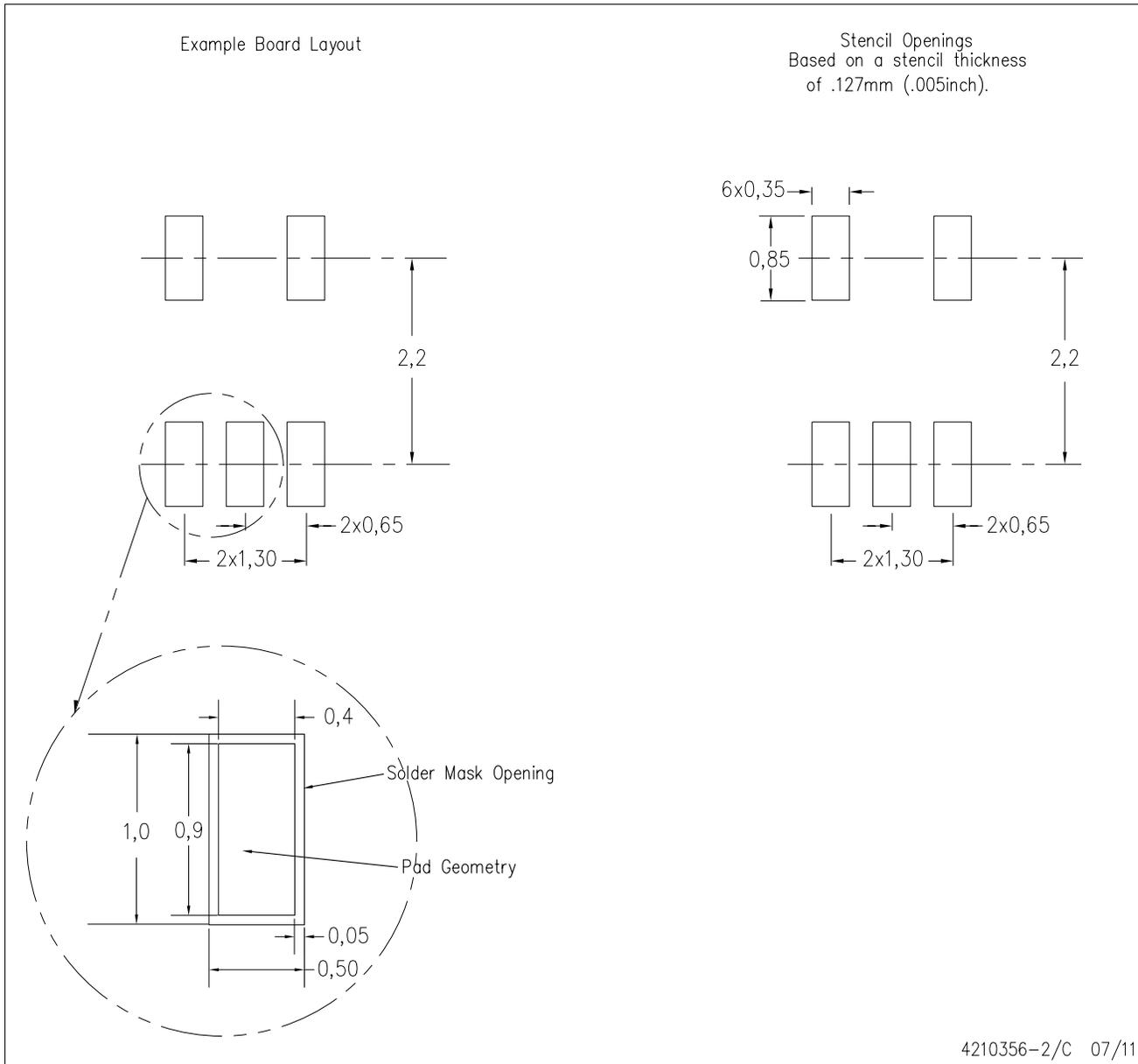
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



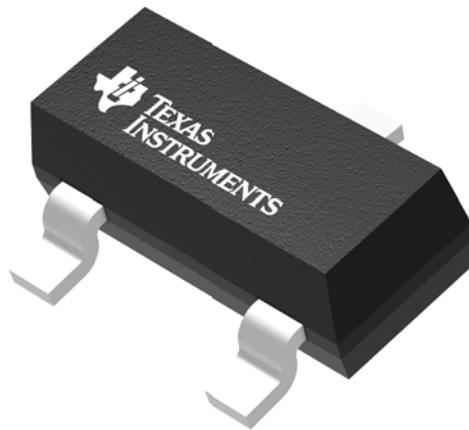
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## GENERIC PACKAGE VIEW

**DBZ 3**

**SOT-23 - 1.12 mm max height**

SMALL OUTLINE TRANSISTOR



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4203227/C

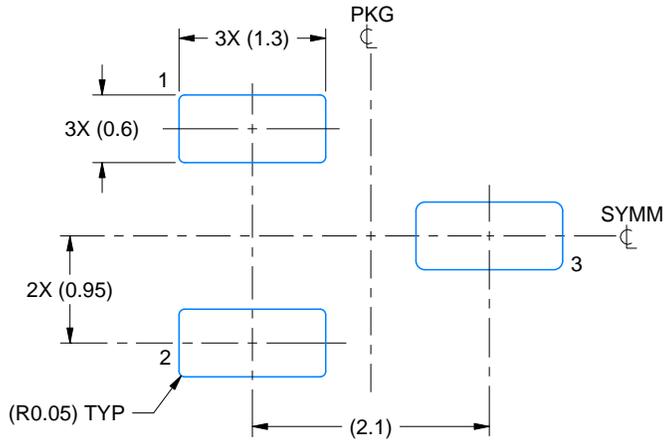


# EXAMPLE BOARD LAYOUT

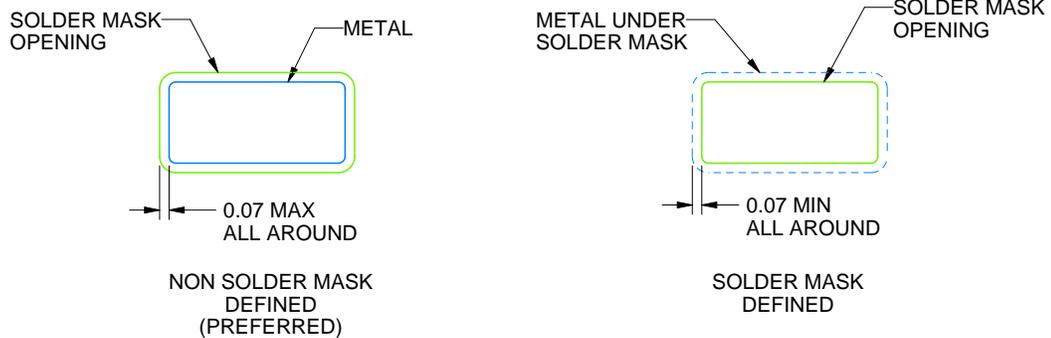
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
SCALE:15X



SOLDER MASK DETAILS

4214838/C 04/2017

NOTES: (continued)

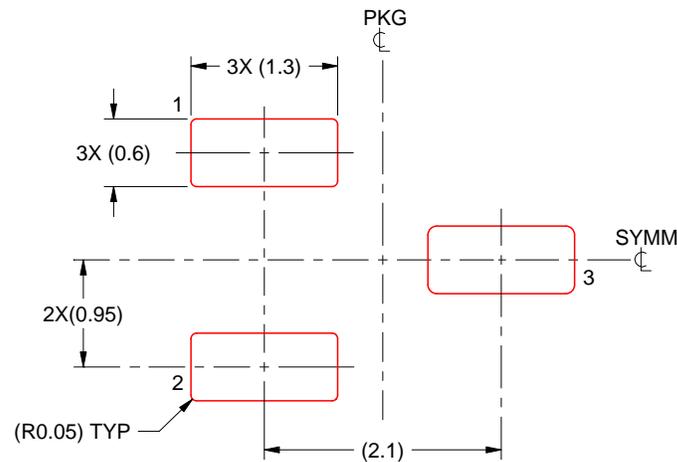
4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:15X

4214838/C 04/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

## 重要声明和免责声明

TI 均以“原样”提供技术性及其可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对TI 及其代表造成的损害。

TI 所提供产品均受TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及ti.com.cn上或随附TI产品提供的其他可适用条款的约束。TI提供所述资源并不扩展或以其他方式更改TI 针对TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122

Copyright © 2020 德州仪器半导体技术（上海）有限公司